

FIG. 1

FIG. 1

**FIG. 2**

FIG. 2 is a cross-sectional view of a device 20. The device 20 includes a top layer 26, a middle layer 24, and a bottom layer 22. The middle layer 24 contains a series of vertical structures 38, which are connected to the bottom layer 22 by a series of vertical structures 42. The bottom layer 22 is shown in cross-section, revealing internal structures 30 and 44. The entire assembly is supported by a base 20.

FIG. 3

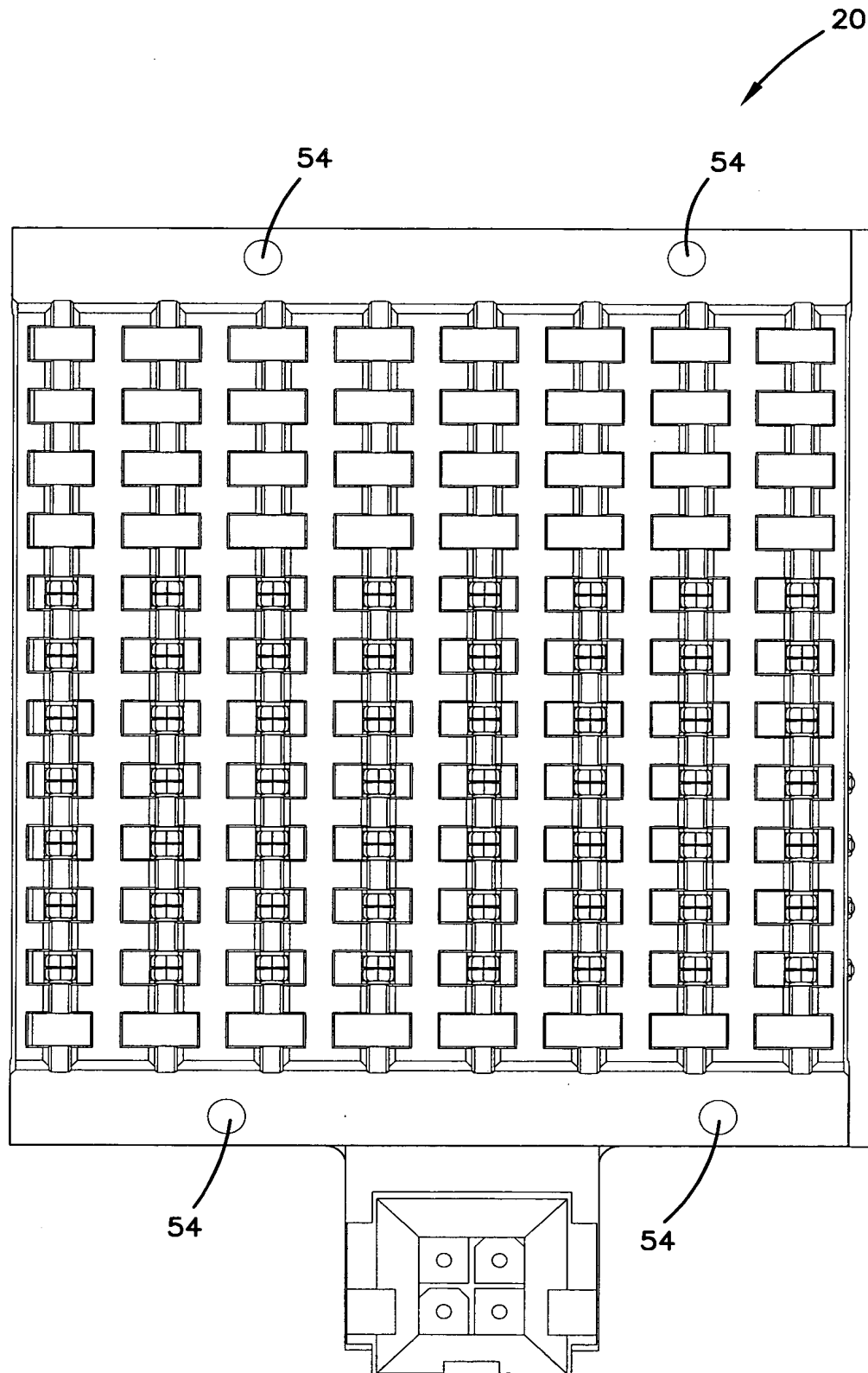


FIG. 3

FIG. 5

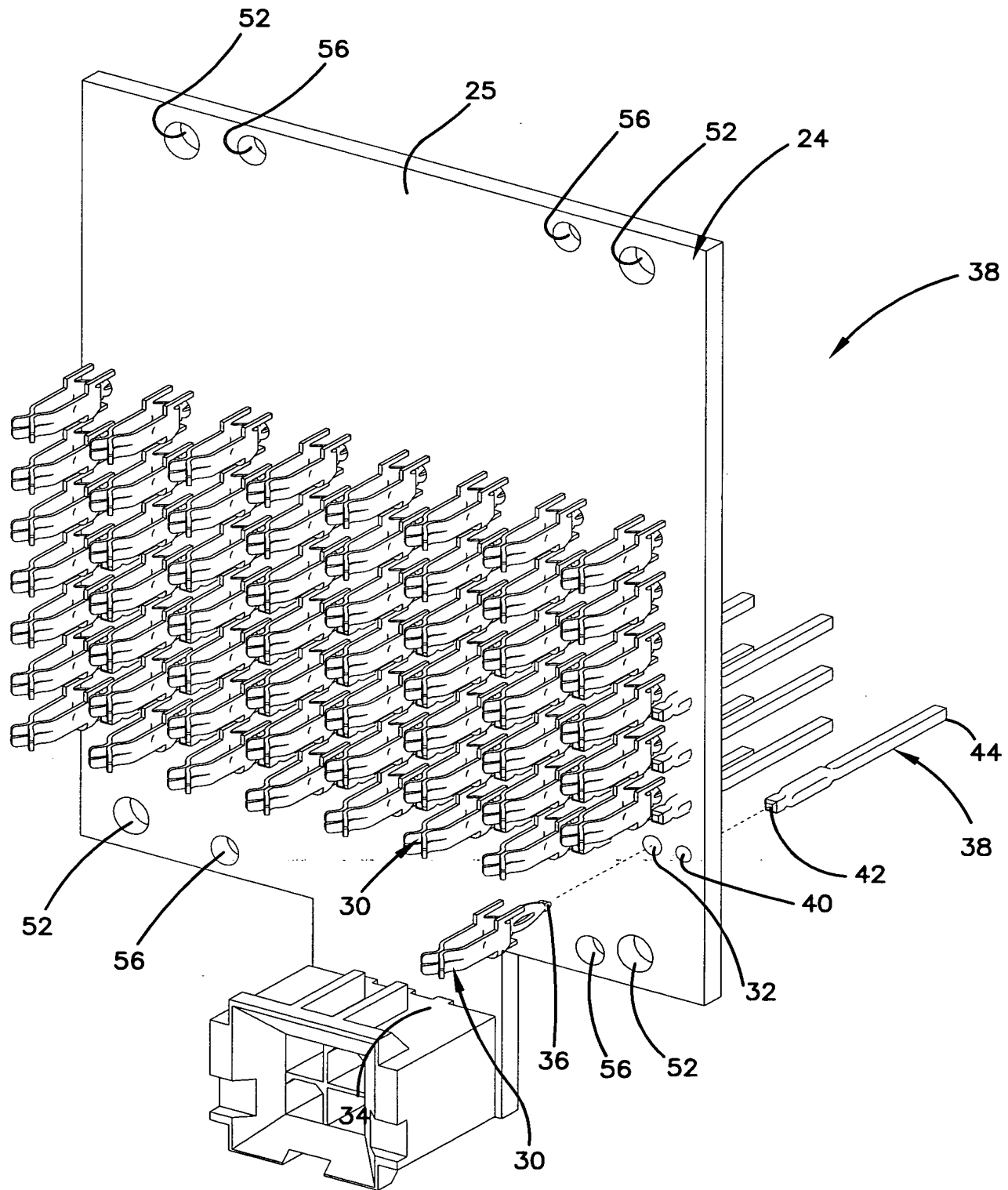


FIG. 6

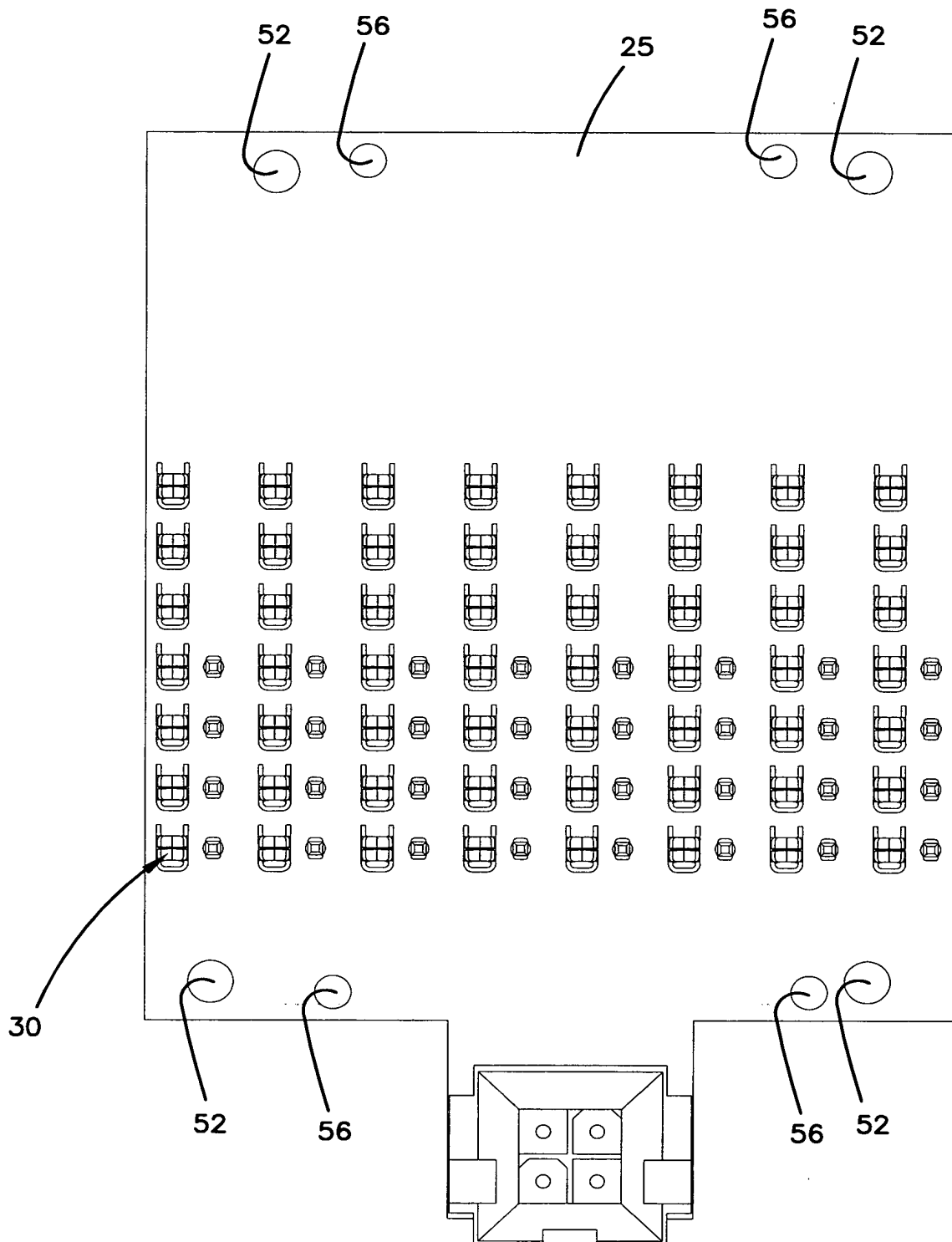


FIG. 6: 612.332.1000

FIG. 7

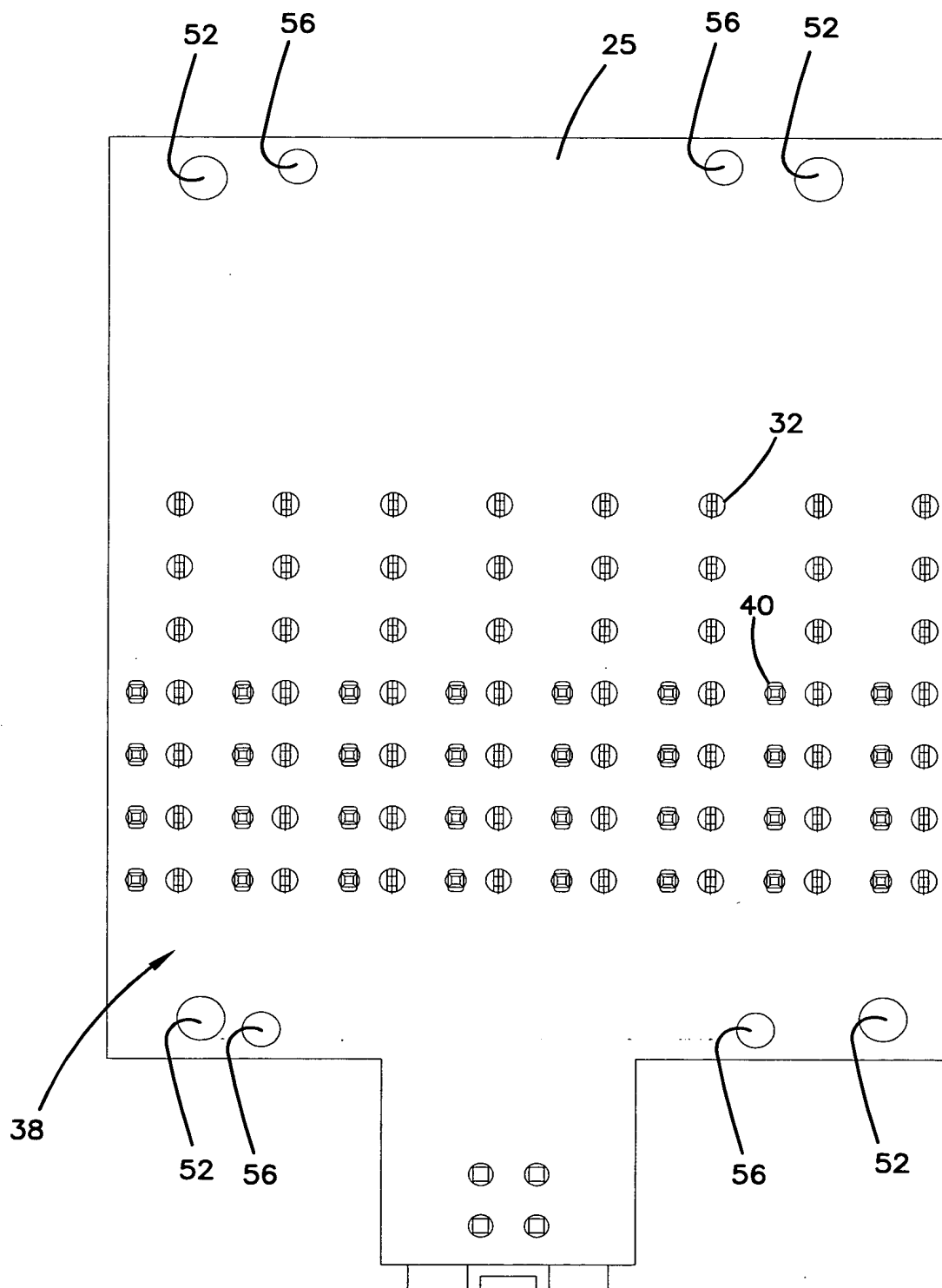


FIG. 7

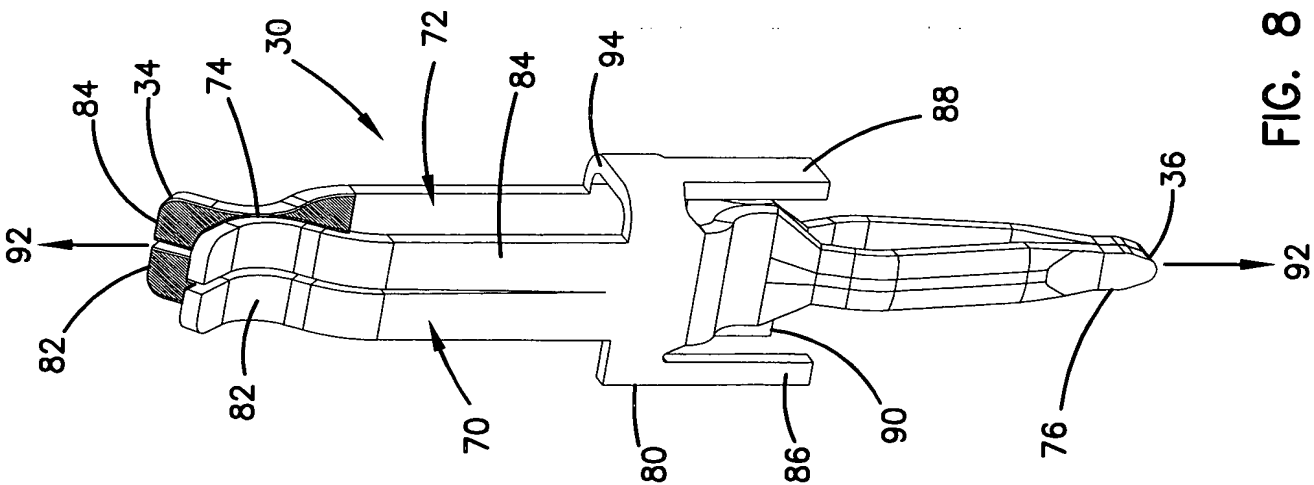


FIG. 8

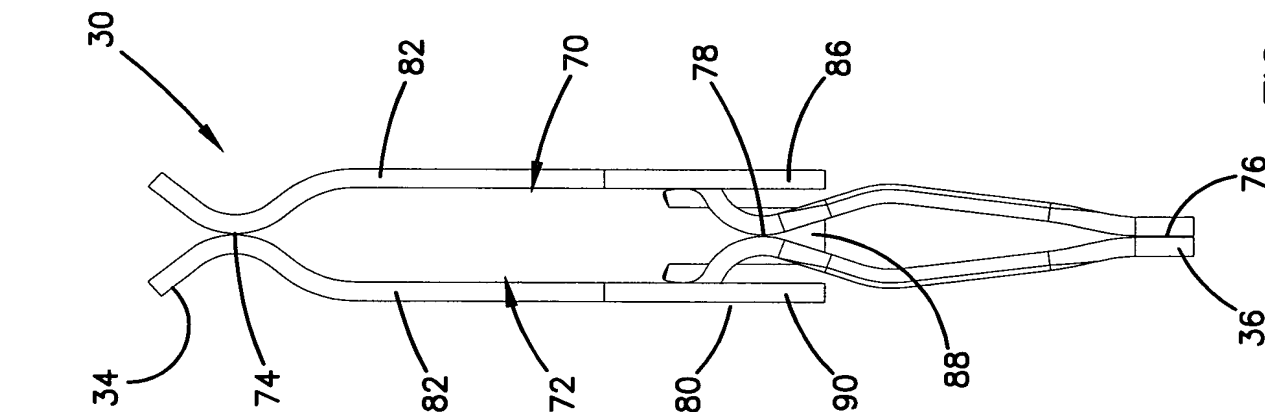


FIG. 9

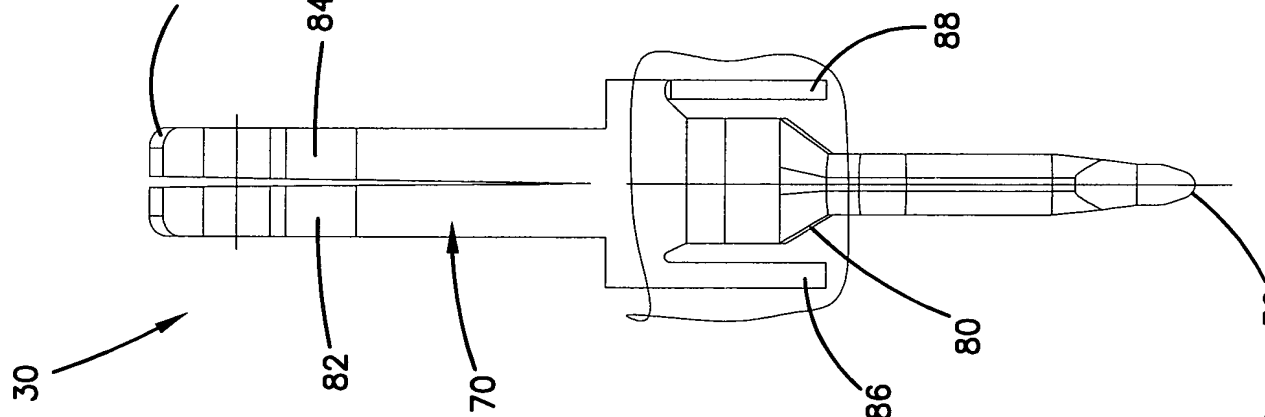


FIG. 10

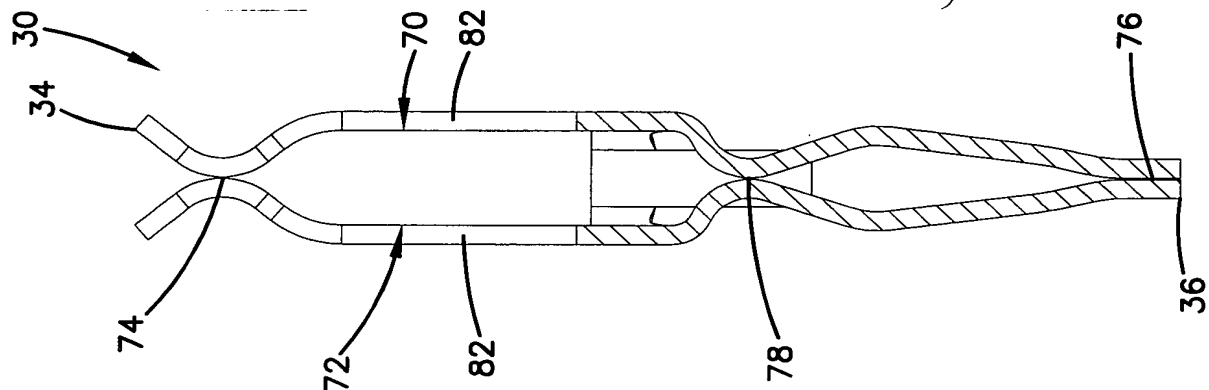


FIG. 13

FIG. 11

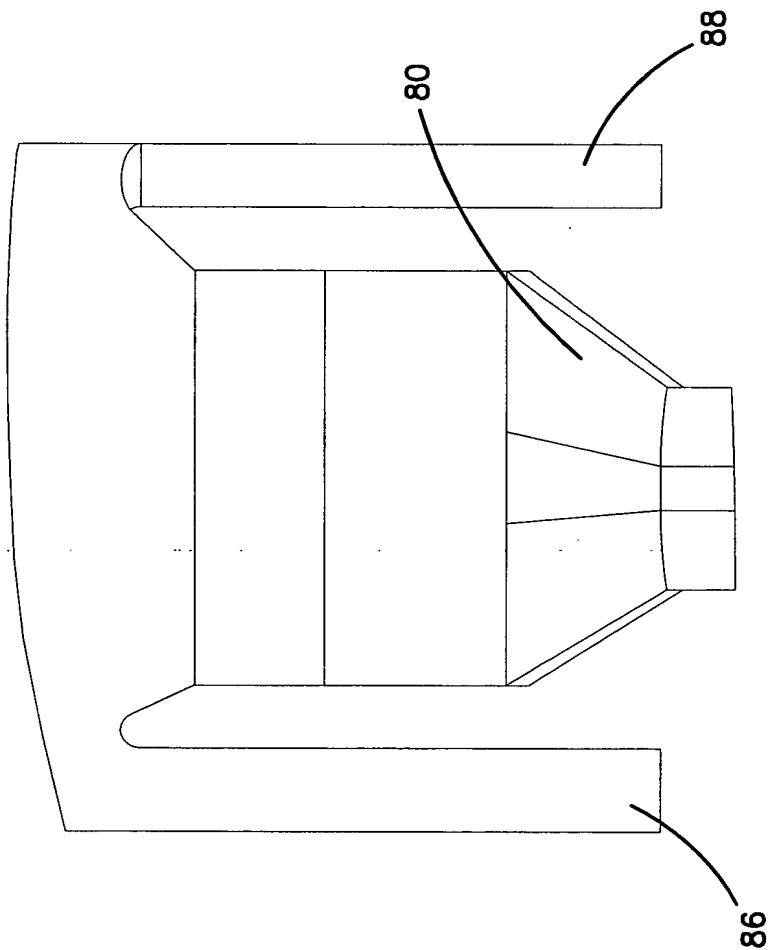


FIG. 11

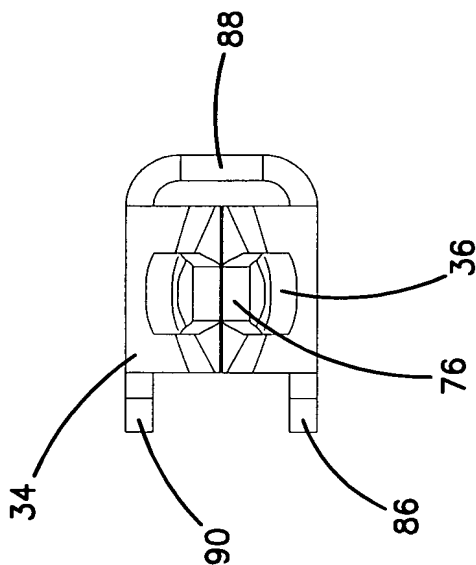


FIG. 12



FIG. 14

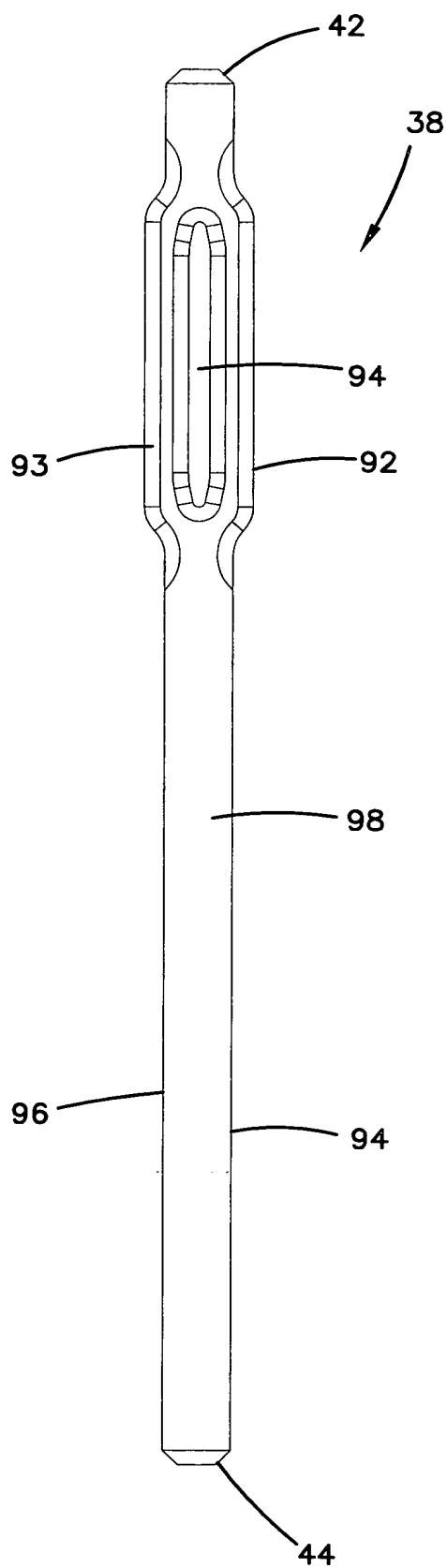


FIG. 15

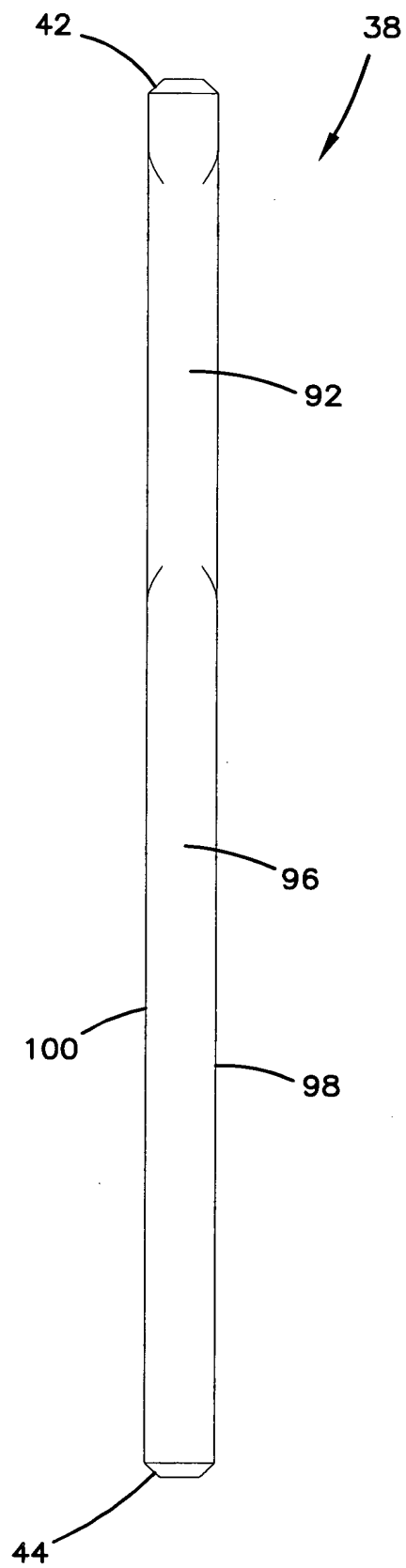


FIG. 14

FIG. 16

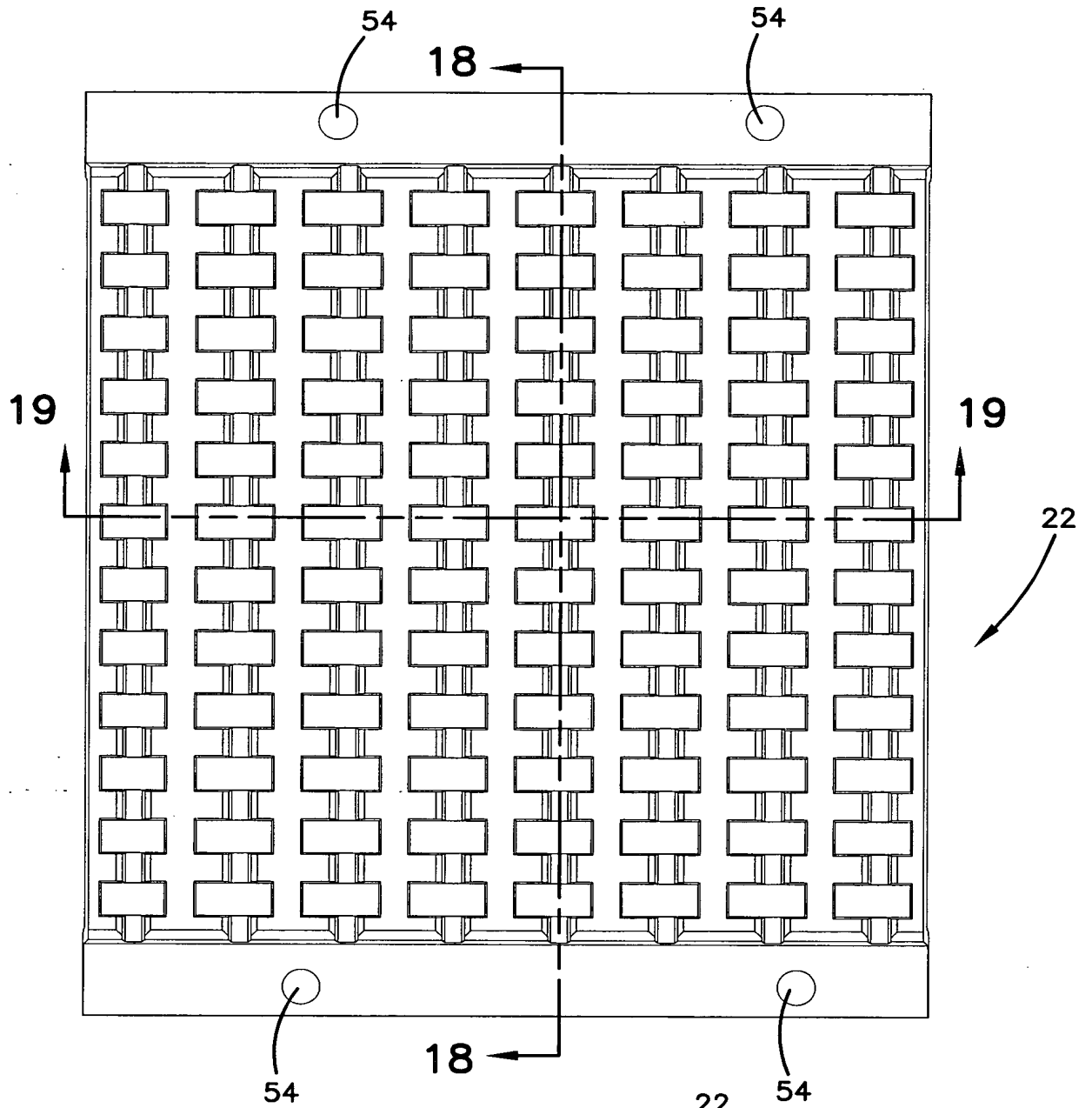
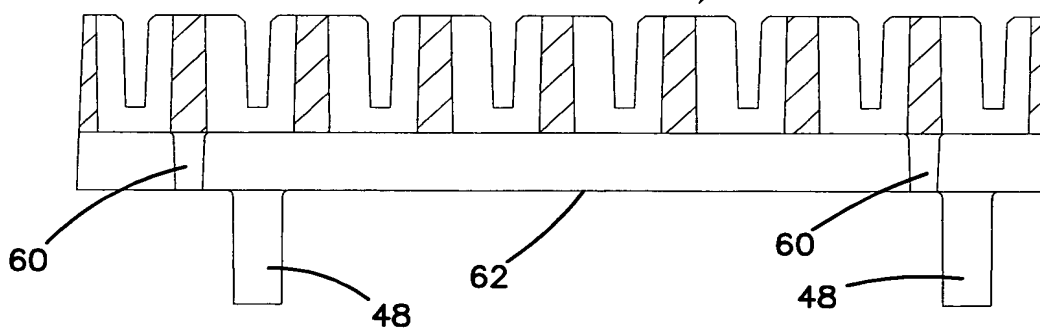


FIG. 19



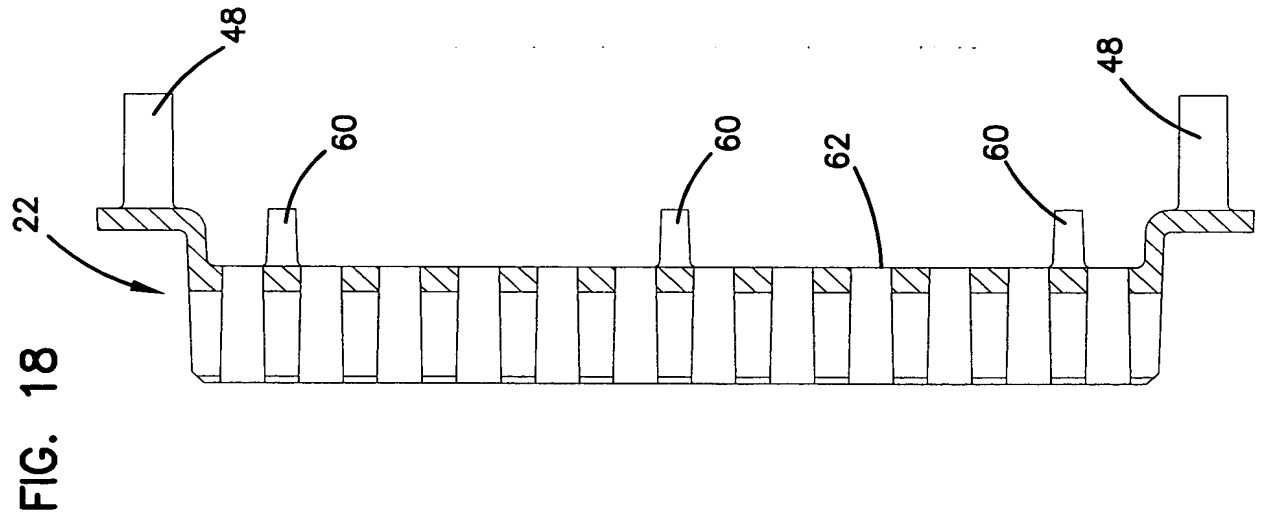
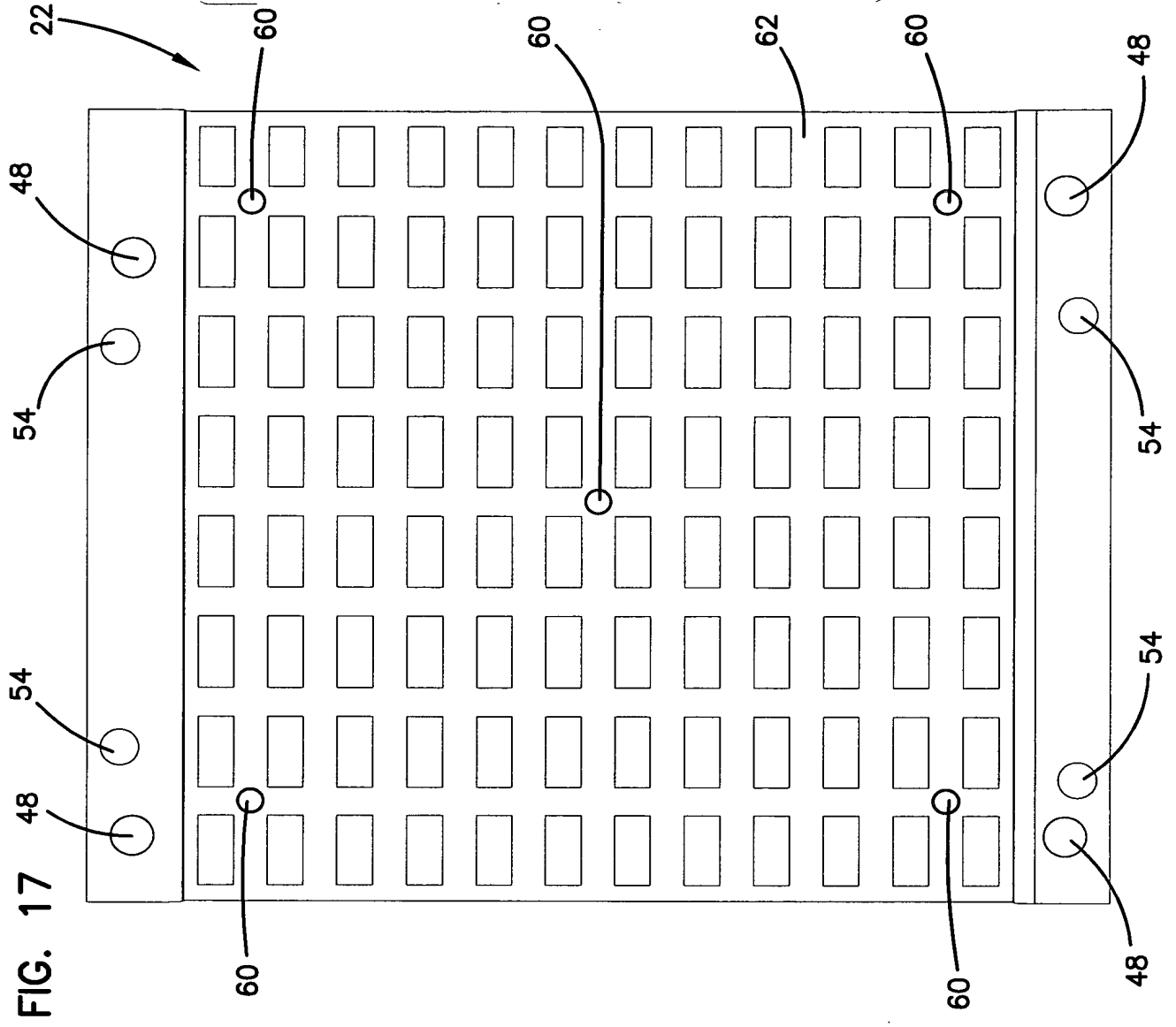


FIG. 17

FIG. 18

FIG. 20

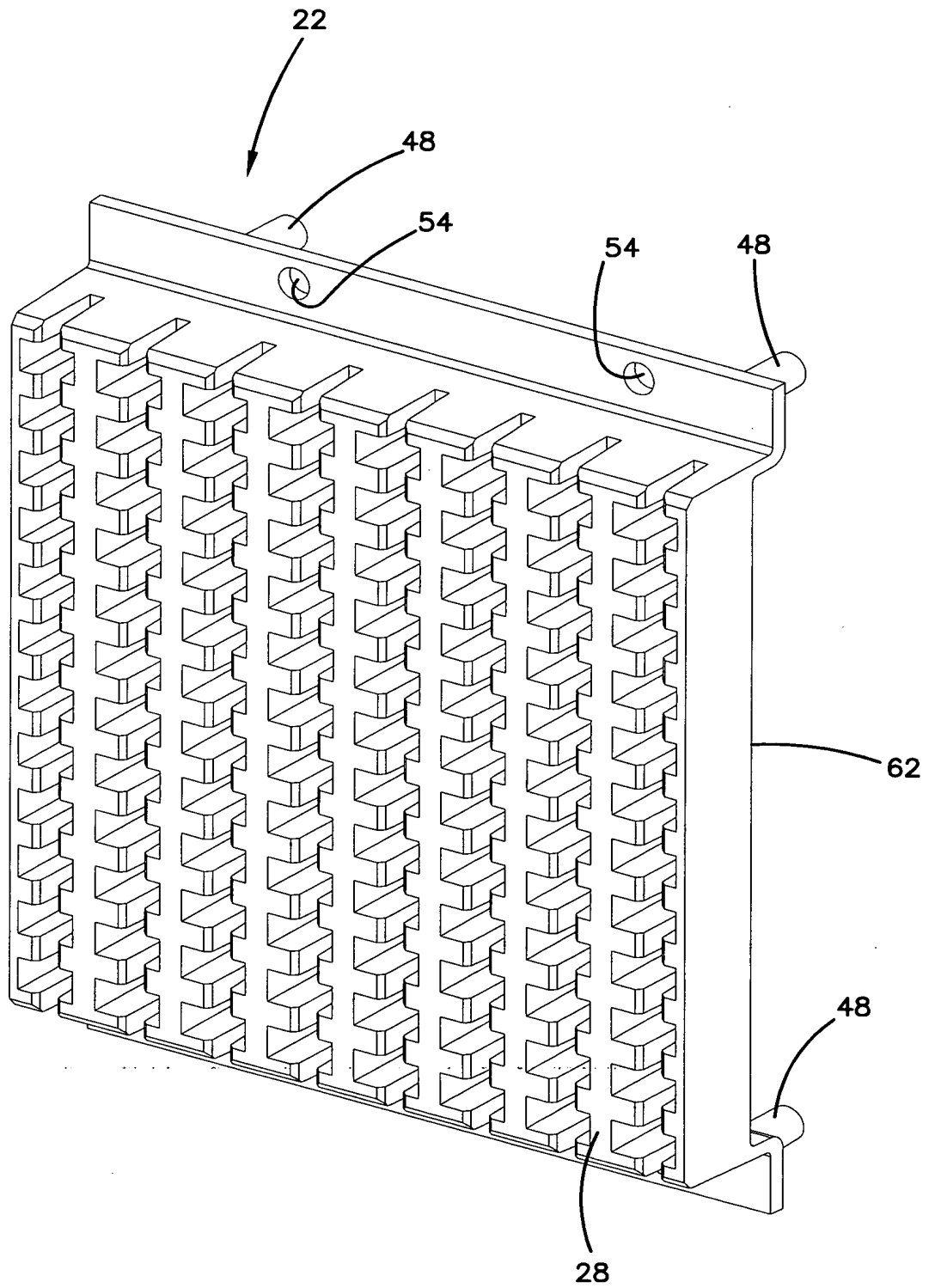


FIG. 20

FIG. 21

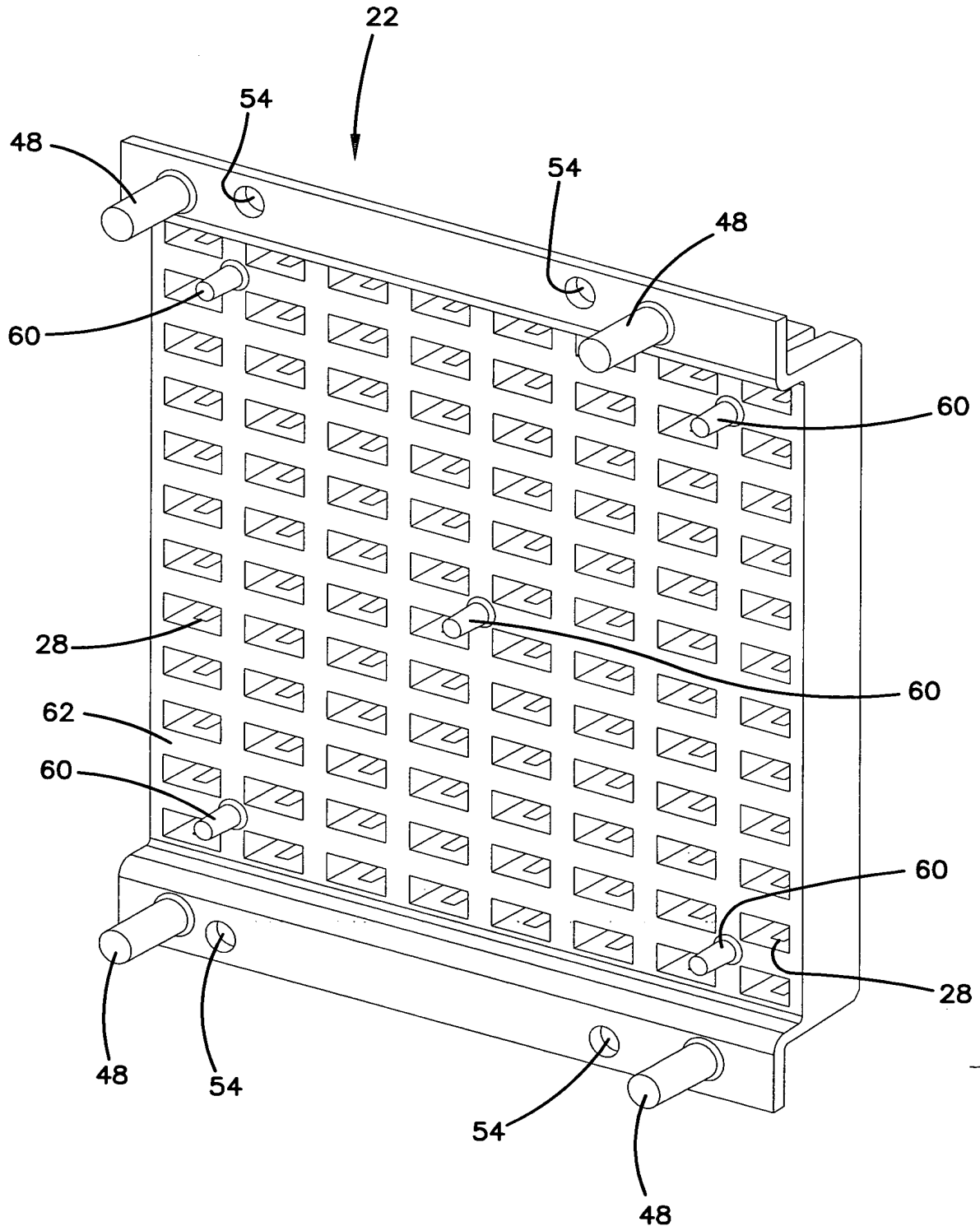
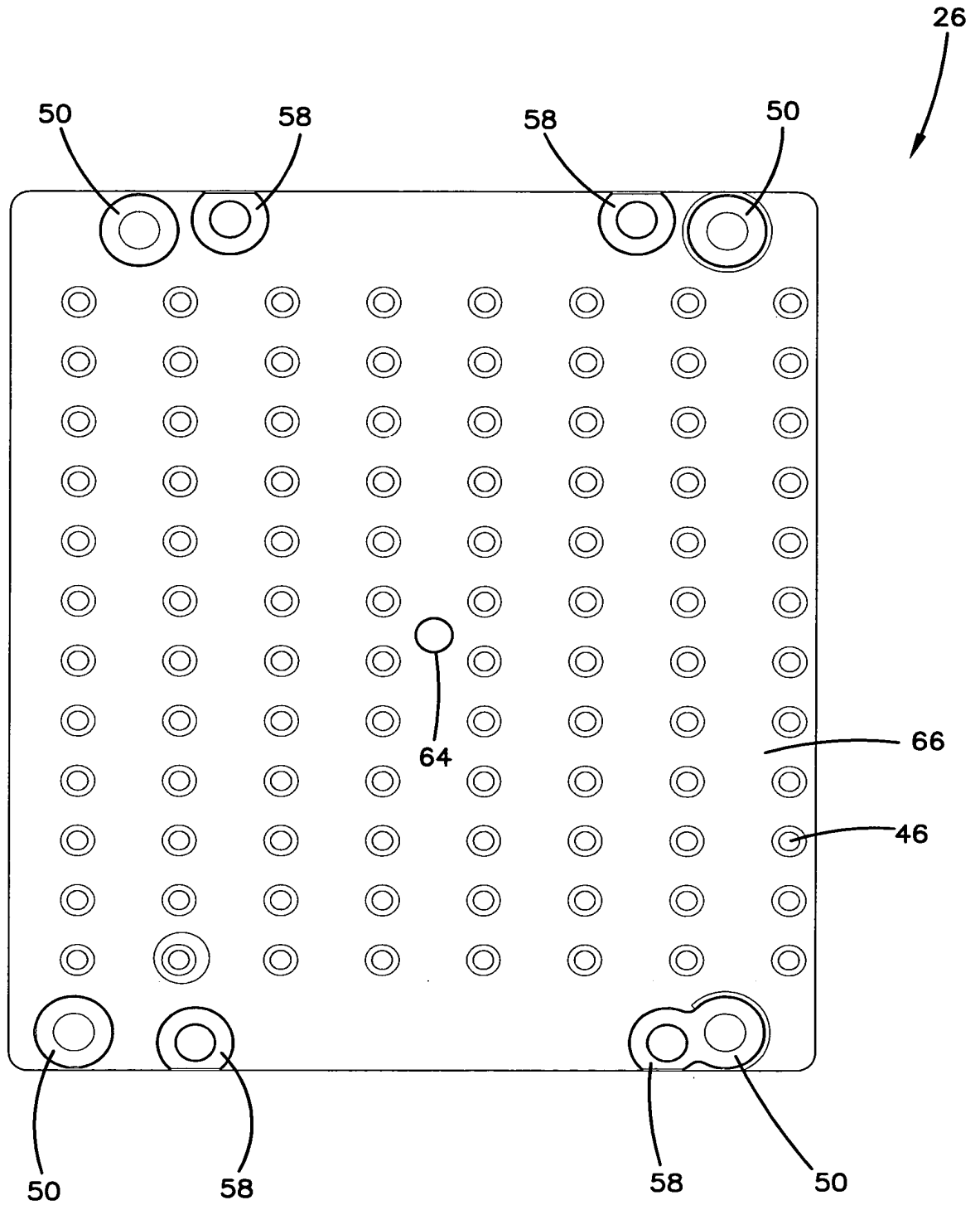


FIG. 22



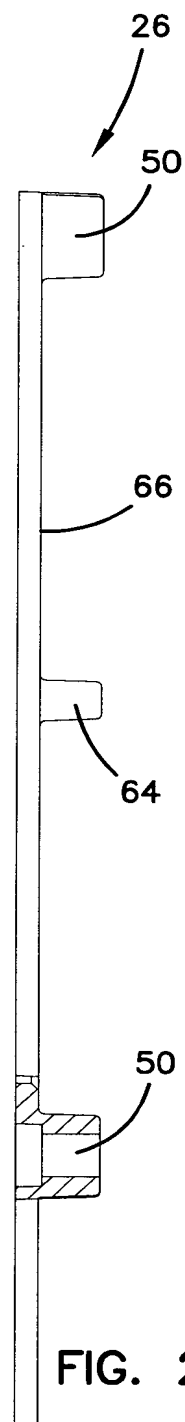
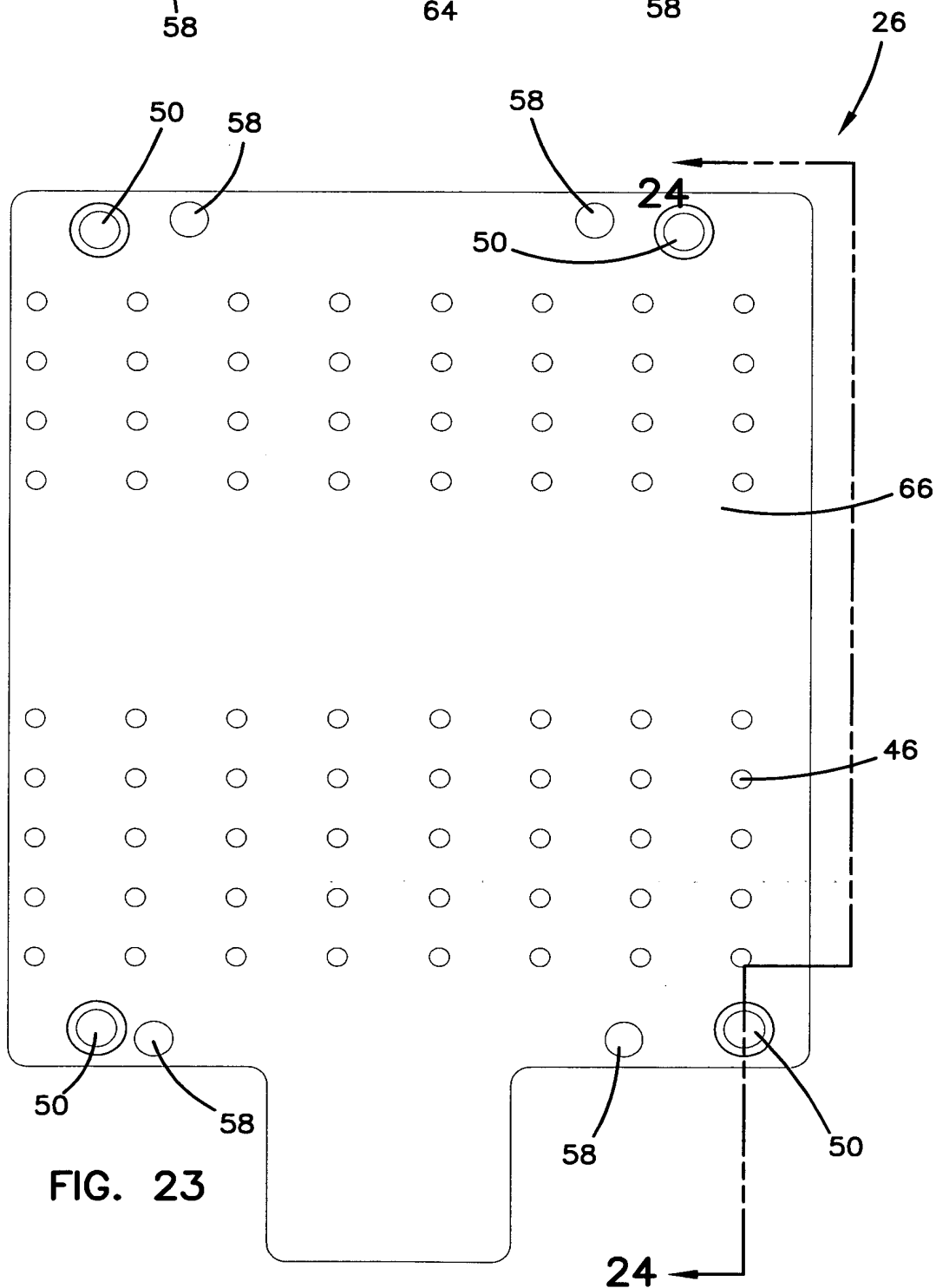
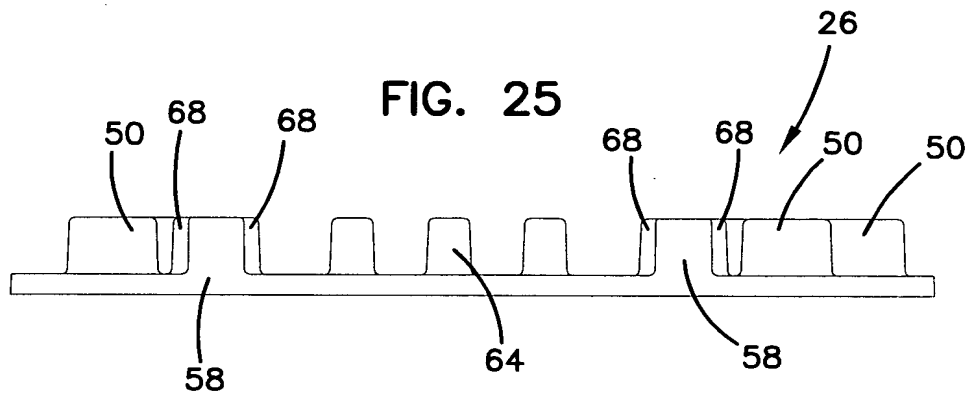
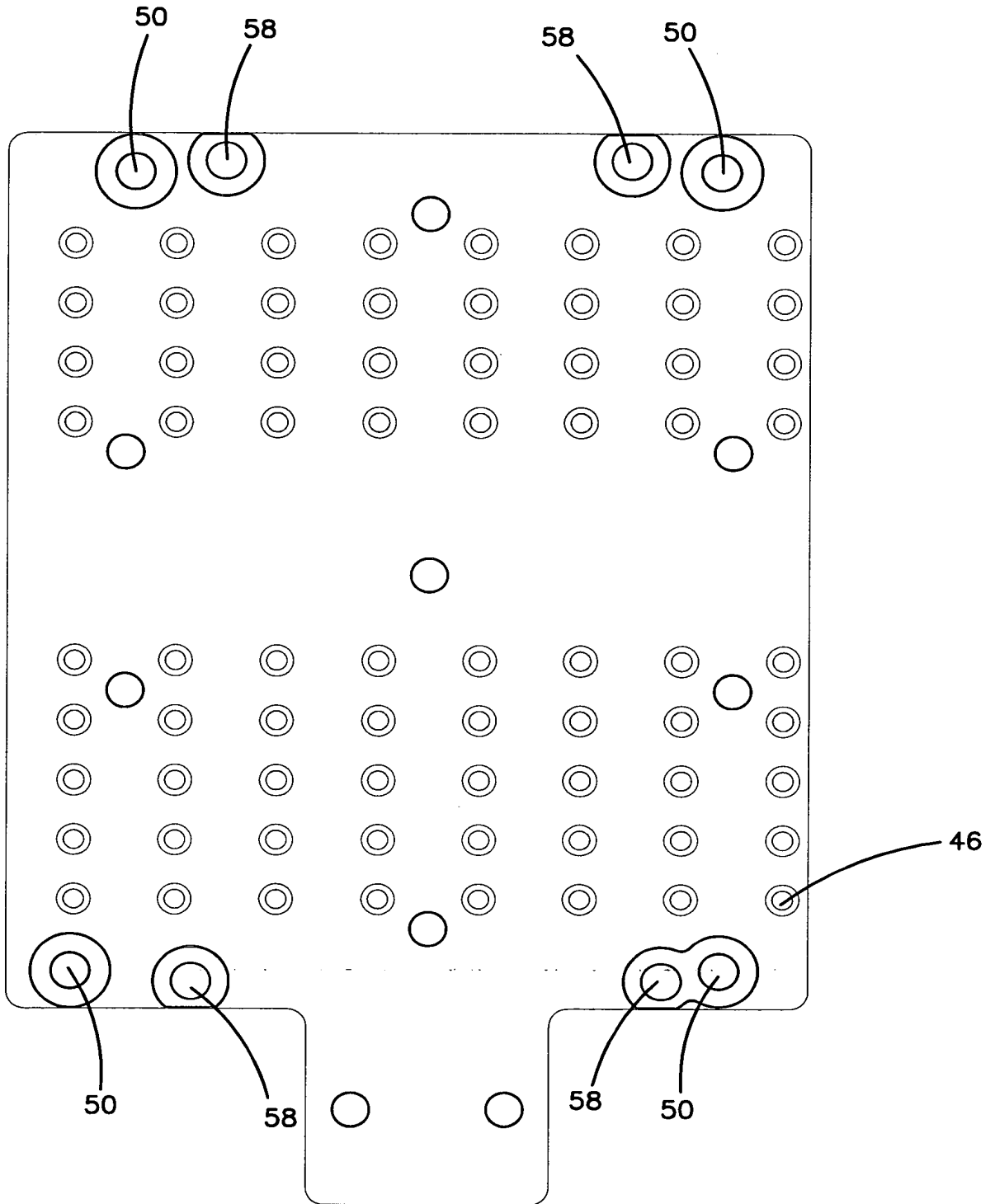


FIG. 26





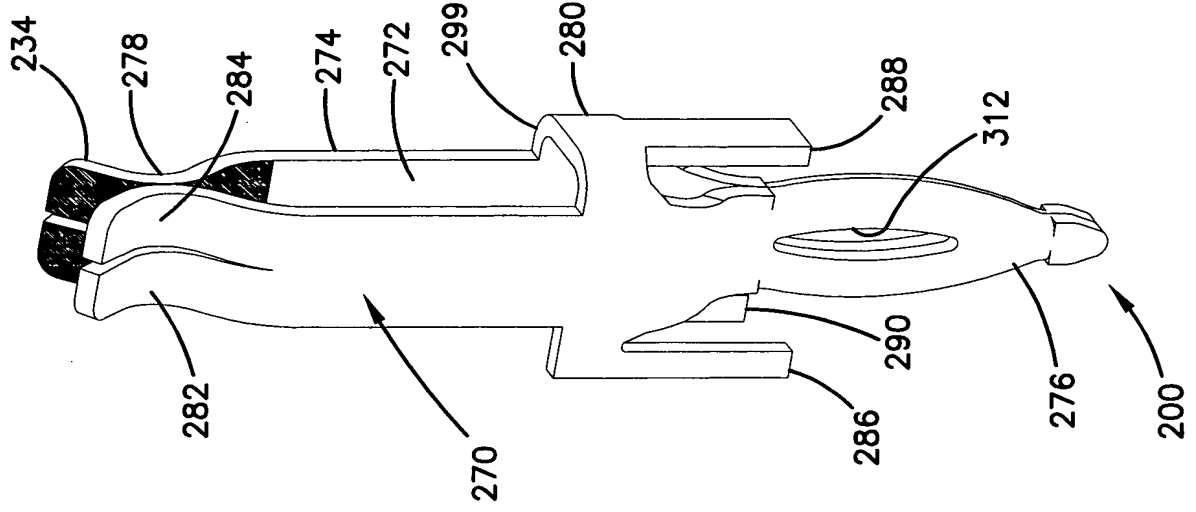


FIG. 27

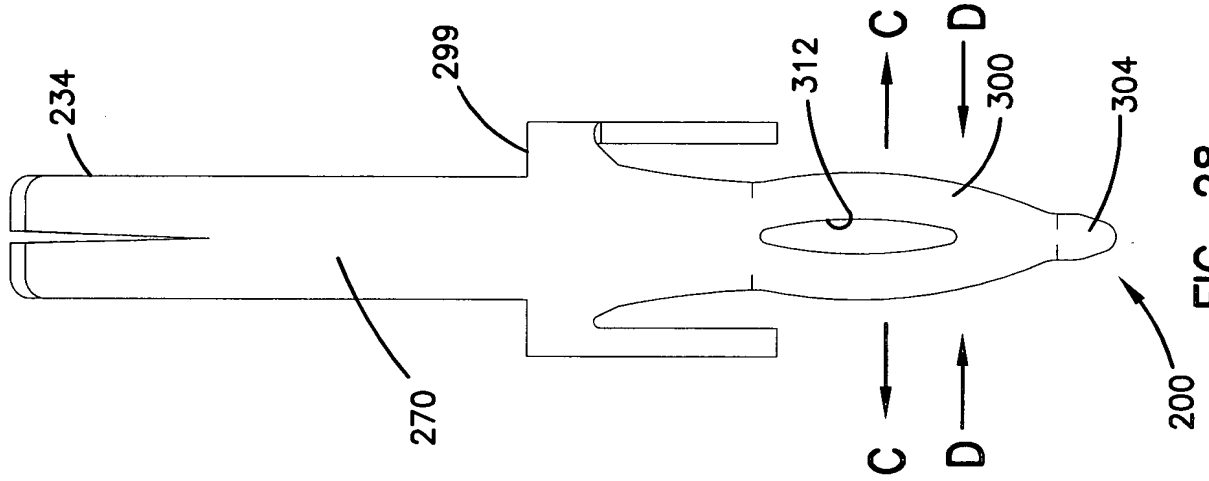


FIG. 28

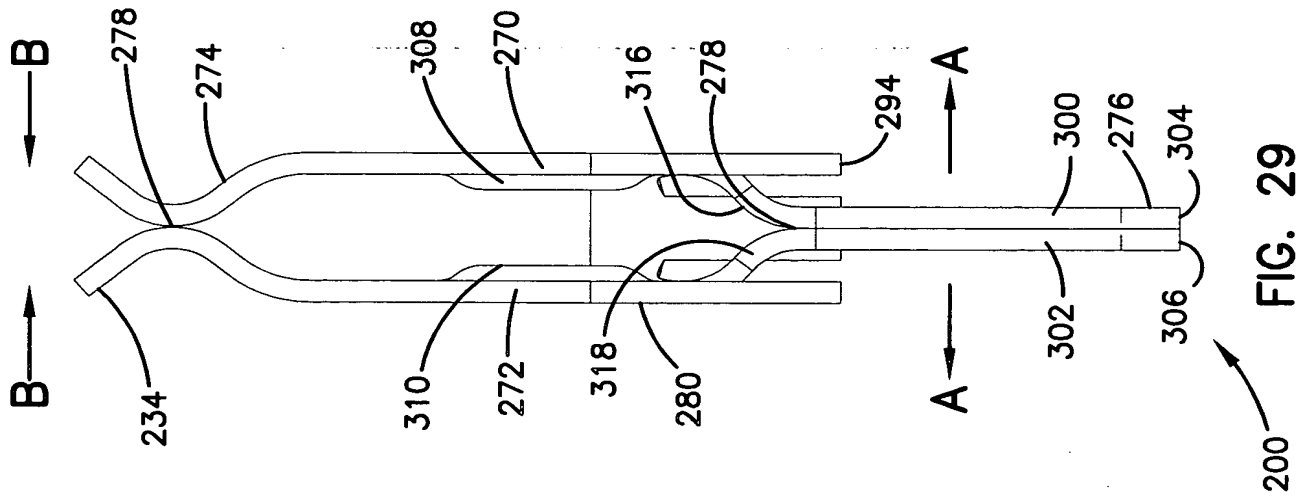


FIG. 29

FIG. 27

FIG. 30

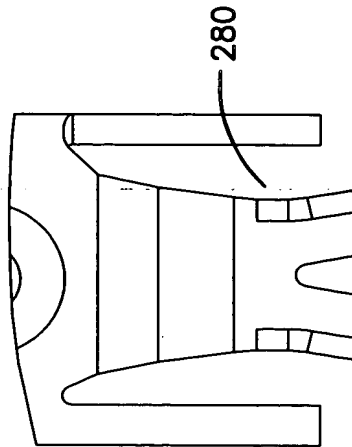


FIG. 30

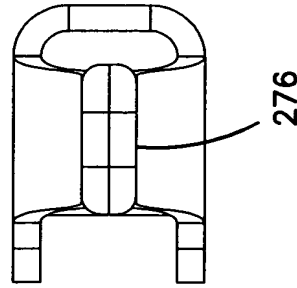


FIG. 31

FIG. 32

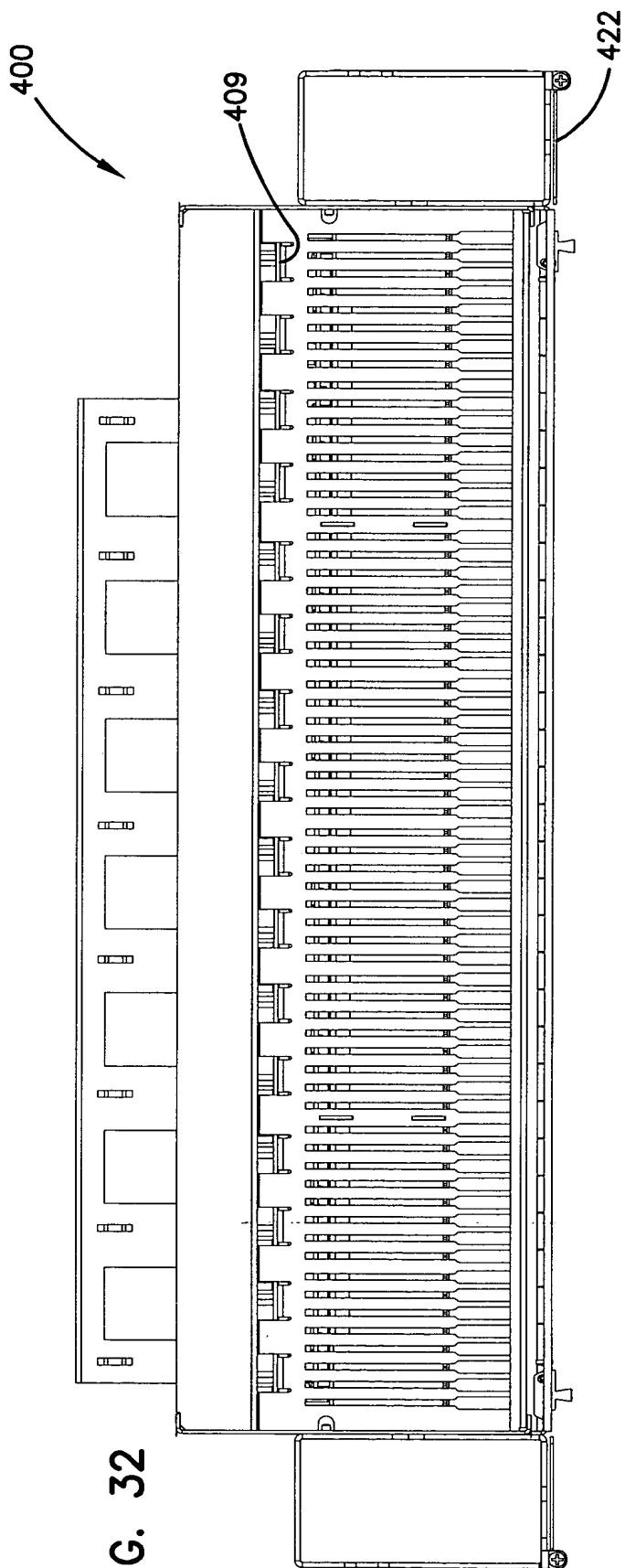
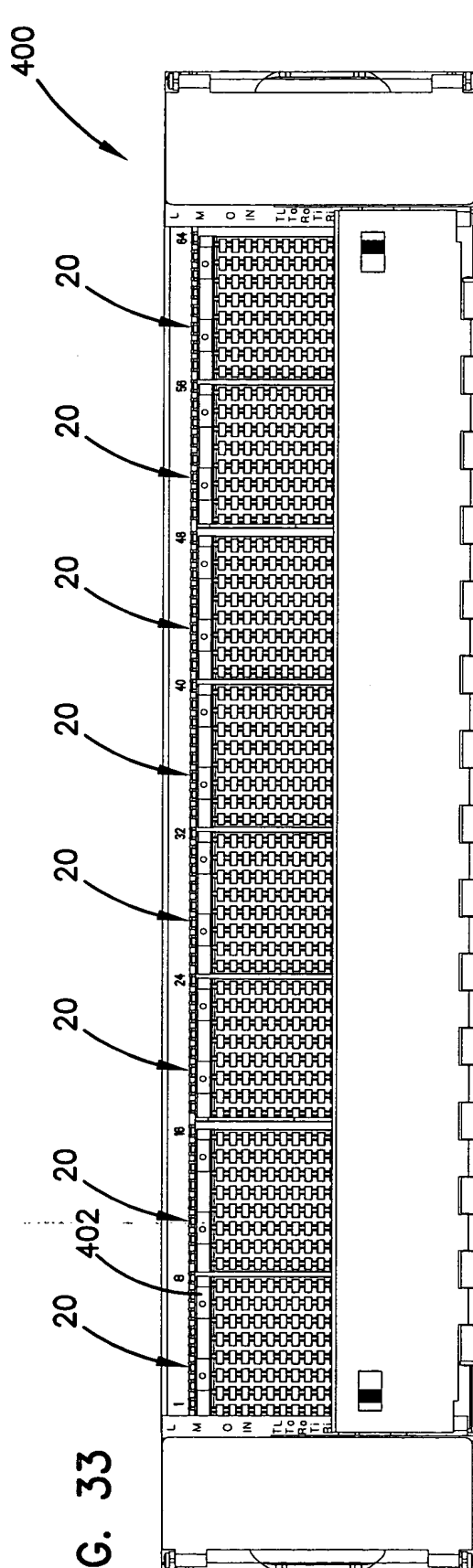


FIG. 33



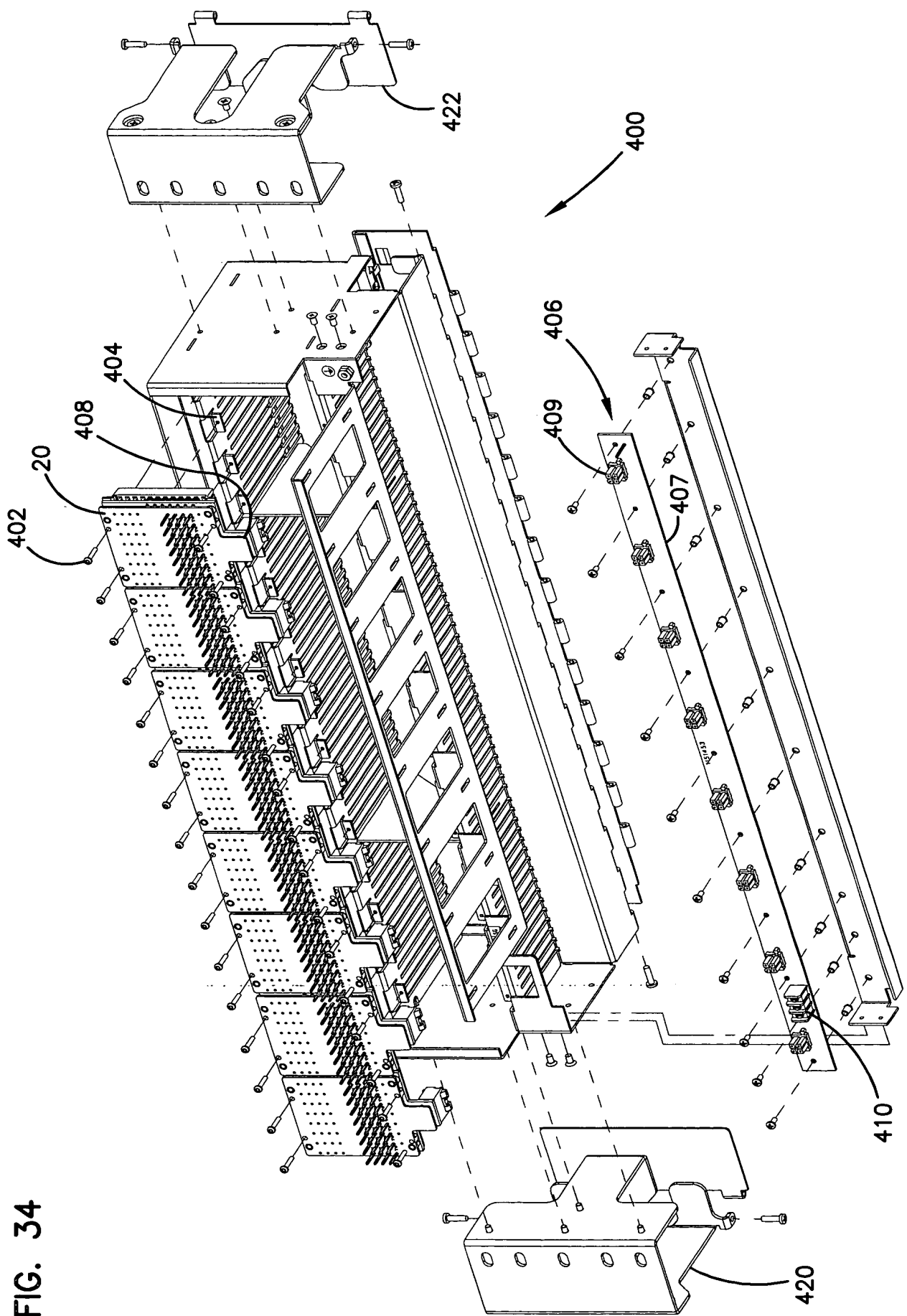


FIG. 34

FIG. 34

FIG. 35

FIG. 35

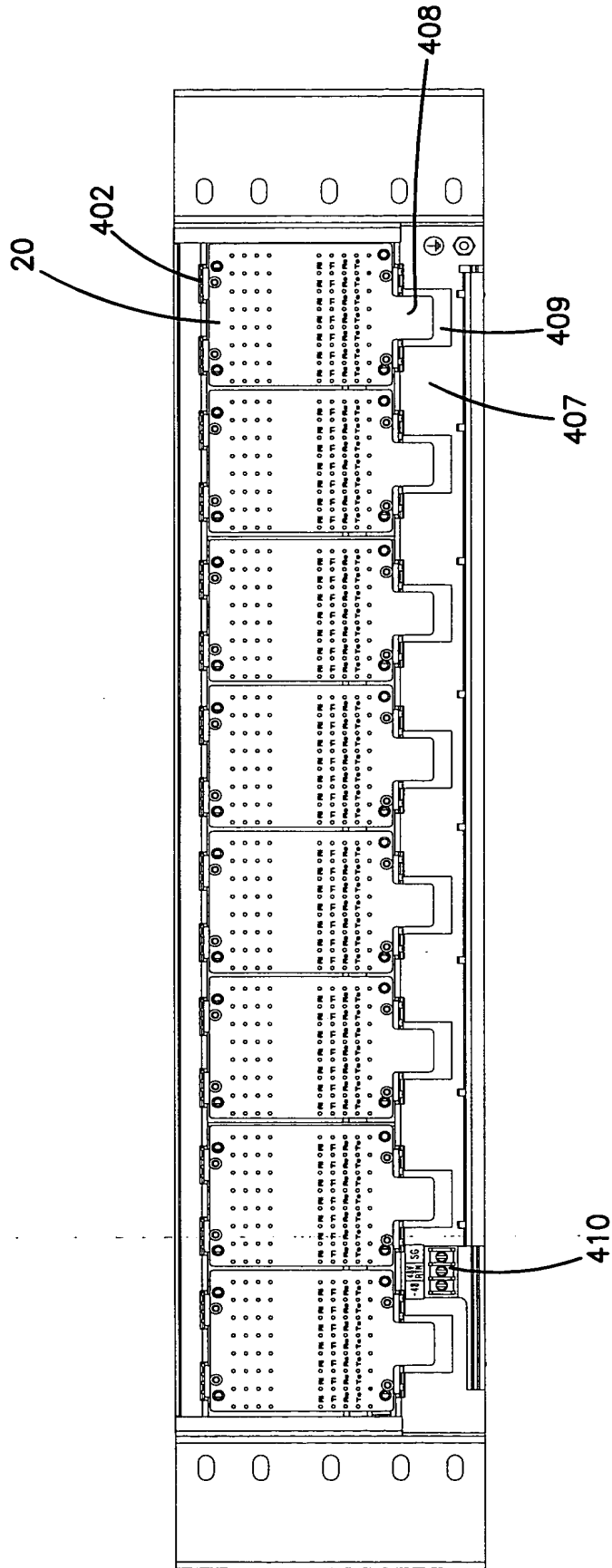


FIG. 36

